

Technical Committees

Computer-Aided Design

L. BESSER
COMSAT General Integrated Syst.
1131 San Antonia Rd.
Palo Alto, CA 94303

Submillimeter-Wave Techniques

K. J. BUTTON
Bldg. NW-14
Massachusetts Inst. Technol.
Cambridge, MA 02133

Microwave and Millimeter-Wave Solid-State Devices

M. COHEN
Westinghouse Defense Electronics
Advanced Technol. Ctr.
Box 1521
Baltimore, MD 21203

H. J. KUNO
Hughes Aircraft Co.
3100 W. Lomita Blvd.
Torrance, CA 90509

Microwave Ferrites

C. R. BOYD, JR.
Microwave Applications Group
3030 Industrial Parkway
Santa Maria, CA 93455

Microwave Systems

J. B. HORTON
TRW 92/3166
One Space Park
Redondo Beach, CA 90278

Microwave Network Theory

A. E. WILLIAMS
COMSAT LABS
22300 Comsat Dr.
Clarksburg, MD 20734

Microwave Acoustics

R. S. KAGIWADA
TRW Defense and Space Syst. Group
Elec. Syst. Div.
1 Space Park
Redondo Beach, CA 90278

Microwave High-Power Techniques

Biological Effects and Medical Applications

J. C. LIN
Dept. Bio.-Eng.
Univ. Illinois, Chicago
Box 4348
Chicago, IL 60680

Microwave Low Noise Techniques

J. J. WHELEHAN, JR.
Eaton Corp. AIL Div.
Walt Whitman Rd.
Melville, NY 11747

Digital Microwave Systems

P. T. GREILING
Hughes Res. Labs.
3011 Malibu Canyon Rd
Malibu, CA 90265

Fiber and Integrated Optics

W. S. C. CHANG
Dep. Elec. Eng. and Computer Sci.
C-014
Univ. California, San Diego
La Jolla, CA 92093

Microwave and Millimeter-Wave Integrated Circuits

D. W. MAKI
Hughes Aircraft Co., Bldg. 231/2019
3100 W. Lomita Blvd.
P.O. Box 2999
Torrance, CA 90509

Microwave Measurements

H. G. OLTMAN, JR.
Hughes Aircraft Co.
Bldg. 268/A54, 8433 Fallbrook Ave.
Canoga Park, CA 91304

Microwave Field Theory

T. ITOH
Dep. Elec. Eng.
The Univ. Texas, Austin, Box 7728
Austin, TX 78712

Automatic RF Techniques

M. A. MAURY, JR.
Maury Microwave Corp.
8610 Helms Ave.
Cucamonga, CA 91730

Technical Committees Chairman

B. E. SPIELMAN
U.S. Naval Res. Lab.
4555 Overlook Ave.
Washington, DC 20375

Vice Chairman

H. J. KUNO

EDITORIAL BOARD

Editor

R. LEVY

S. Adam
A. T. Adams
K. K. Agarwal
J. Amoss
D. B. Anderson
J. A. Arnaud
J. R. Ashley
A. E. Atia
N. F. Audeh
A. J. Bahr
J. W. Bandler
H. E. M. Barlow
F. S. Barnes
R. H. T. Bates
E. F. Belohoubek
P. Bhartia
J. Bradshaw
D. I. Breitzer
M. Brodwin
C. Buntschuh
J. J. Burke
H. Bussey
K. J. Button
C. A. Cain
H. J. Carlin
P. H. Carr
K. S. Champlin
K. Chang
W. S. C. Chang
M. Chodorow
J. Citerne
S. B. Cohn
R. E. Collin
H. M. Cronson
E. Cristal
W. R. Curtice
J. B. Davies
L. E. Davis
M. E. Davis
J. E. Degenford
E. Denlinger

L. E. Dickens
C. H. Durney
W. J. English
G. W. Farnell
L. B. Felsen
Z. Galani
R. V. Garver
V. G. Gelinovatch
J. W. Gewartowski
A. Gopinath
H. Gruenberg
K. C. Gupta
M. S. Gupta
A. W. Guy
U. Gysel
G. I. Haddad
M. A. K. Hamid
R. F. Harrington
W. Harth
H. L. Hartnagel
G. L. Heiter
J. Helszajn
M. E. Hines
W. J. R. Hoefer
W. E. Hord
J. B. Horton
M. C. Horton
A. Q. Howard, Jr.
H. Howe, Jr.
W. J. Ince
M. Iskander
T. Itoh
R. Jansen
P. B. Johns
W. R. Johns
A. K. Jordan
D. Kajfez
A. J. Kelly
A. R. Kerr
P. Khan
D. D. Khandelwal
R. H. Knerr

Y. Konishi
A. Konrad
M. K. Krage
J. G. Kretzschmar
W. Ku
H. J. Kuno
R. Levy
L. Lewin
I. V. Lindell
S. L. March
D. Marcuse
D. Masse
G. L. Matthaei
M. A. Maury, Jr.
P. R. McIsaac
M. W. Medley, Jr.
J. W. Mink
N. Morita
W. W. Mumford
Y. Naito
H. Okean
T. Okoshi
A. A. Oliner
K. Oscar
C. Pask
D. Parker
J. Perini
B. S. Perlman
D. F. Peterson
R. A. Pucel
J. P. Quine
C. Rauscher
C. Ren
J. D. Rhodes
E. Rivier
G. P. Rodrigue
A. E. Ros
A. Rosen
F. J. Rosenbaum
S. W. Rosenthal
H. E. Rowe

T. E. Rozzi
C. T. Rucker
A. A. M. Saleh
E. W. Sard
W. O. Schlosser
M. V. Schneider
W. E. Schroeder
H. Schwan
A. K. Sharma
Y.-C. Shih
P. Silvester
H. Sobol
P. I. Somlo
A. W. Snyder
R. V. Snyder
K. Solbach
W. Steenaart
W. H. Steier
Y. Takayama
C. H. Tang
J. J. Taub
V. Tripathi
W. C. Tsai
R. S. Tucker
A. Uhler, Jr.
W. A. G. Voss
J. J. Wang
H. C. Wang
J. A. Weiss
W. T. Weeks
S. H. Wemple
R. J. Wenzel
H. A. Wheeler
J. J. Whelehan, Jr.
L. A. Whicker
J. F. White
A. G. Williamson
I. Wolff
E. Yamashita
G. L. Yip
L. Young

INFORMATION FOR AUTHORS

IEEE TRANSACTIONS ON MICROWAVE THEORY AND TECHNIQUES is published monthly. Manuscripts should be prepared especially for publication in this TRANSACTIONS and submitted to the Editor, Ralph Levy, KW Engineering, 4565 Ruffner Street, San Diego, CA 92111. The manuscripts must be typed double-spaced on 22 × 28 cm (8½ × 11 in) sheets. Four copies of both the manuscript and accompanying illustrations should be submitted. A list of illustrations should be included in each copy of the manuscript. Original illustrations should not be submitted initially. They will be called for if the paper is accepted for publication. Also, an author whose manuscript is accepted as a PAPER (but not as a SHORT PAPER) is requested to submit a short biography and a clear, glossy portrait upon acceptance. Each manuscript must include an abstract of not more than 200 words and the complete address of the corresponding author. The Editor reserves the right to return without a review manuscripts exceeding approximately 20 double-spaced typewritten pages plus 20 figures. LETTERS are generally limited to comments and replies to material previously published in this TRANSACTIONS, suggestions for new work, errata, and other exceptionally short articles. "Information for IEEE authors" is available upon request from the IEEE Publications Department, 345 East 47th Street, New York, NY 10017.

Copyright

It is the policy of the IEEE to own the copyright to the technical contributions it publishes on behalf of the interest of the IEEE, its authors, and their employers, and to facilitate the appropriate reuse of this material by others. To comply with the U.S. Copyright Law, authors are required to sign an IEEE Copyright Form before publication. This form, a copy of which appears in each January issue of this TRANSACTIONS, returns to authors and their employers full rights to reuse their material for their own purposes. Authors must submit a signed copy of this form with their manuscripts.

Clearance of Manuscripts

The IEEE must of necessity assume that materials presented at its meetings or submitted to its publications are properly available for general dissemination to the audiences these activities are organized to serve. It is the responsibility of the author, not the IEEE, to determine whether disclosure of their material requires the prior consent of other parties, and if so, to obtain it.

Publication Policy

Papers will be reviewed for their technical merit, and decisions to publish will be made independently of an author's ability or willingness to pay page charges. *Voluntary page charges* of \$110 per printed page will be requested for papers of five pages or less. Page charges of \$110 per page are mandatory for each page in excess of five printed pages. Also, the MTT-S Administrative Committee has established a quota for the number of pages printed in each issue of this TRANSACTIONS whose costs are not defrayed by payment of page charges. Papers not covered by page charges may be delayed until space in an issue is available. The Editor can waive the quota requirement for exceptional papers or because of other extenuating circumstances.